

**Final Product Change Notification**

201811009F01

**Issue Date:** 01-Jan-2019  
**Effective Date:** 15-Apr-2019  
 Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.  
 For detailed information we invite you to [view this notification online](#)



**Change Category**

- |   |  |  |   |   |
|---|--|--|---|---|
| <input checked="" type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input checked="" type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location             | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Release of 8 inch wafer diameter for general-purpose Schottky diodes

**Details of this Change**

Release of 8 inch wafer diameter for general-purpose Schottky diodes and Schottky barrier rectifiers. In addition the top side metallization of the affected diodes will be adapted for standarization reasons.

Old products: Production using 6 inch wafer diameter, top side metallization with 1.6µm

Changed products: Production using 6 and 8 inch wafer diameter, top side metallization with 1.5µm (for 8 inch wafer)

Selected types have a change of wire material from Au to Cu with release of 2nd source mold compound and release of lead frame design version SOT323 R1 that have been announced for structurally similar types with precvious PCNs as denoted in attached document.

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

**Why do we Implement this Change**

To increase flexibility and volume ramp-up.

**Identification of Affected Products**

The 8 inch products can be identified by a marker on the die surface.

Changed products can be identified by date code after implementation.

## Product Availability

### Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 31-Jan-2019.

### Production

Planned first shipment 01-May-2019

## Impact

No impact to the products' functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted.

Supply using 6 inch wafer will be continued.

## Related Notifications

Notification	Issue Date	Effective Date	Title
201011012F	13-Dec-2010		Change of bond wire material from gold to copper in SOT23 package and 8 inch wafer diameter
201308016F01	14-Dec-2013	14-Mar-2014	Change of bond wire material from Au to Cu and release of 2nd source mold compound
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
201411005F01	26-Jan-2015	10-May-2015	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT363
201712005F01	30-Apr-2018	29-Jul-2018	Change of lead frame version in SOT323 package
201807002F01U01	103-Oct-2018	11-Jan-2019	Release of 8 inch wafer diameter for PMEG4010EPK

## Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 31-Jan-2019. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact Nexperia "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

## About Nexperia B.V.

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Nexperia B.V.  
Jonkerbosplein 52 6534 AB Nijmegen, The Netherlands

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